TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (High Speed U-MOSII)

# TPC8105-H

High Speed and High Efficiency DC-DC Converters
Lithium Ion Battery Applications
Notebook PCs

Portable Equipment Applications

• Small footprint due to small and thin package

• High speed switching

• Small gate charge : Qg = 32 nC (typ.)

• Low drain-source ON resistance  $: RDS (ON) = 20 \text{ m}\Omega \text{ (typ.)}$ 

• High forward transfer admittance :  $|Y_{fs}| = 12 \text{ S (typ.)}$ 

• Low leakage current :  $I_{DSS} = -10 \mu A (max) (V_{DS} = -30 V)$ 

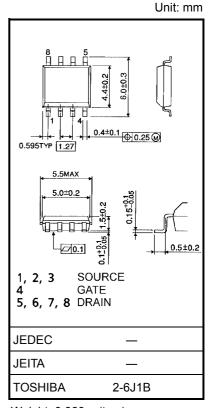
• Enhancement-mode :  $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA)}$ 

#### Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage (R	R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	-30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-7	Α	
Diam current	Pulse (Note 1)	$I_{DP}$	-28	A	
Drain power dissipati	on (t = 10 s) (Note 2a)	$P_{D}$	2.4	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P <sub>D</sub>	1.0	W	
Single pulse avalance	ne energy (Note 3)	E <sub>AS</sub>	63.7	mJ	
Avalanche current		I <sub>AR</sub>	-7	Α	
Repetitive avalanche (	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.24	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	-55 to 150	°C	

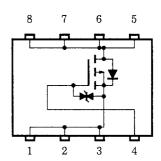
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

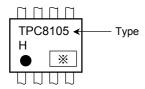
### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

### Marking (Note 5)

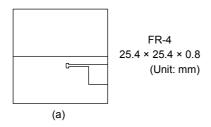


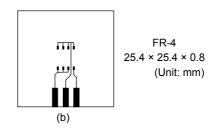
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

(a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3:  $V_{DD}$  = -24 V,  $T_{ch}$  = 25°C (initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = -7 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature.

Note 5: ● on lower left of the marking indicates Pin 1.

\* shows Lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: january to december are denoted by letters A to L respectively)

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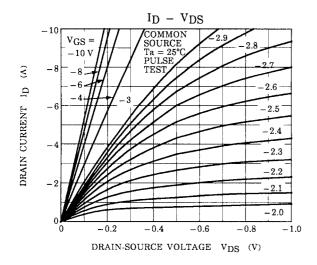
# **Electrical Characteristics (Ta = 25°C)**

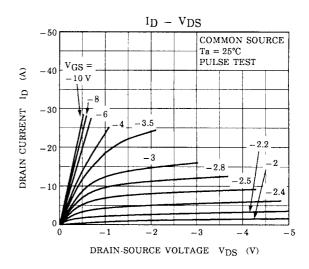
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V		_	-10	μA
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	1	1	V
		V <sub>(BR)DSX</sub>	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15	1	1	
Gate threshold v	oltage	$V_{th}$	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = -4 \text{ V}, I_D = -3.5 \text{ A}$	_	34	60	mΩ
		R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -3.5 \text{ A}$	_	20	40	
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -3.5 A	5.9	12	_	S
Input capacitano	:e	C <sub>iss</sub>		_	1440	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	330	_	pF
Output capacitance		C <sub>oss</sub>		_	485	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = \frac{0 \text{ V}}{10 \text{ V}} = \frac{10 \text{ F}}{10 \text{ V}} = \frac{-3.5 \text{ A}}{10 \text{ V}}$ $R_{L} = \frac{4.3 \Omega}{4.3 \Omega}$ $V_{DD} = -15 \text{ V}$ $Duty \le 1\%, t_{W} = 10 \mu \text{s}$	_	10	_	
	Turn-on time	t <sub>on</sub>			18	1	ne
	Fall time	t <sub>f</sub>			50		ns ns
	Turn-off time	t <sub>off</sub>		_	140	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	32	_	
Gate-source charge		$Q_{gs}$	$V_{DD} \approx -24 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7 \text{ A}$	_	23	_	nC
Gate-drain ("miller") charge		$Q_{gd}$		_	8	_	

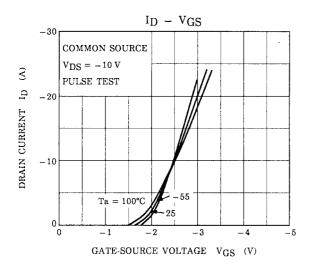
# Source-Drain Ratings and Characteristics (Ta = 25°C)

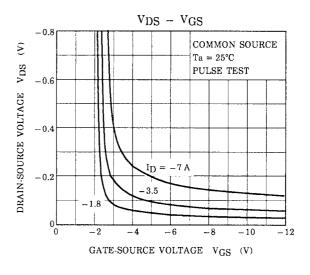
Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	ı	ı	ı	-28	Α
Forward voltage (	(diode)	$V_{DSF}$	$I_{DR} = -7 \text{ A}, V_{GS} = 0 \text{ V}$			1.2	V

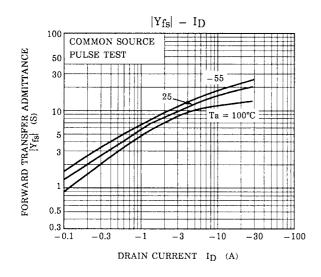
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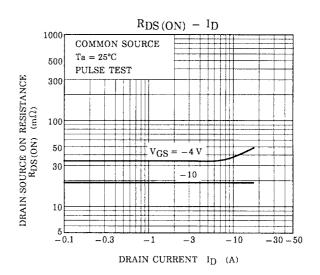


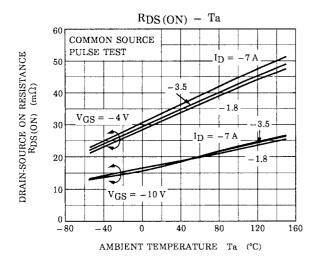


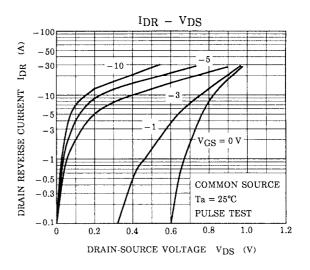


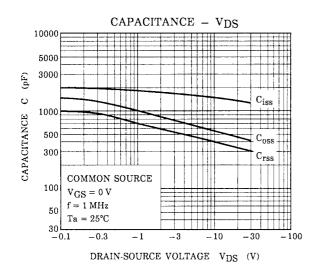


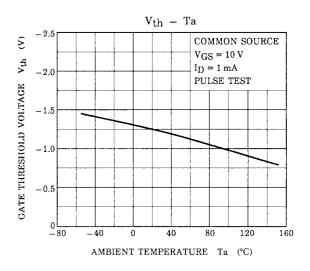


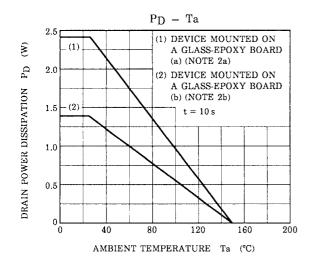


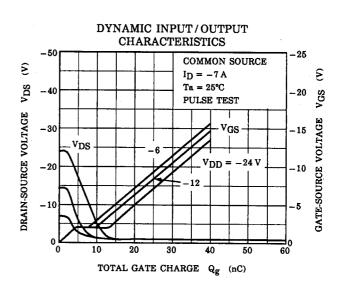




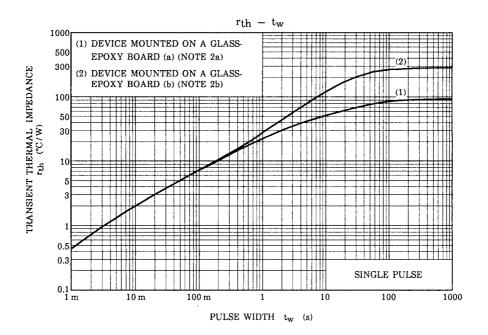


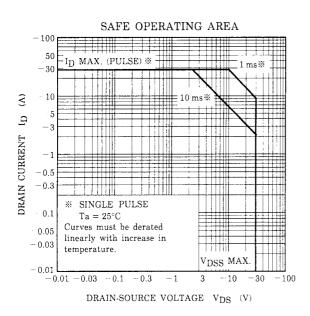


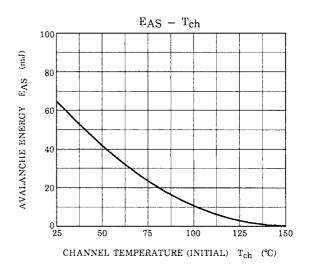


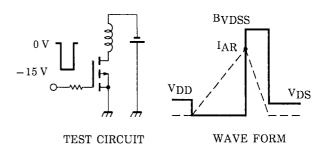


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$$\begin{array}{ll} T_{ch} = 25^{\circ}C \; (\mathrm{Initial}) \\ Peak \; I_{AR} = -7 \; A, \; R_G = 25 \; \Omega \end{array} \quad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot (\frac{B_{VDSS}}{B_{VDSS} - V_{DD}}) \\ V_{DD} = -24 \; V, \; L = 1.0 \; mH \end{array}$$

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